



PSMN012-100YSF

NextPower 100 V, 11.8 mOhm N-channel MOSFET in LFAK56 package

20 June 2023

Product data sheet

1. General description

NextPower 100 V, standard level gate drive MOSFET. Qualified to 175 °C and recommended for industrial and consumer applications.

2. Features and benefits

- Low Q_{rr} for higher efficiency and lower spiking
- Low $Q_G \times R_{DS(on)}$ FOM for high efficiency switching applications
- Strong avalanche energy rating (E_{AS})
- Avalanche rated and 100% tested
- Ha-free and RoHS compliant LFAK56 package
- Wave-solderable LFAK56 package

3. Applications

- Synchronous rectifier in AC-DC and DC-DC
- Primary side switch in 48 V DC-DC
- BLDC motor control
- USB-PD and mobile fast-charge adapters
- Flyback and resonant topologies

4. Quick reference data

Table 1. Quick reference data

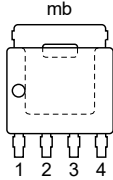
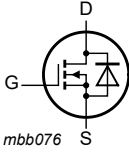
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$	-	-	100	V
I_D	drain current	$V_{GS} = 10\text{ V}$; $T_{mb} = 25\text{ °C}$; Fig. 2	-	-	65	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; Fig. 1	-	-	130	W
T_j	junction temperature		-55	-	175	°C
Static characteristics						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$; $I_D = 20\text{ A}$; $T_j = 25\text{ °C}$; Fig. 12	-	9.7	11.8	mΩ
		$V_{GS} = 10\text{ V}$; $I_D = 20\text{ A}$; $T_j = 100\text{ °C}$; Fig. 13	-	15	18.8	mΩ
Dynamic characteristics						
Q_{GD}	gate-drain charge	$I_D = 20\text{ A}$; $V_{DS} = 50\text{ V}$; $V_{GS} = 10\text{ V}$; $T_j = 25\text{ °C}$; Fig. 14 ; Fig. 15	1.7	5.6	12.8	nC
$Q_{G(tot)}$	total gate charge		14.6	29	44	nC
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 27.8\text{ A}$; $V_{sup} \leq 100\text{ V}$; $R_{GS} = 50\text{ Ω}$; $V_{GS} = 10\text{ V}$; $T_{j(init)} = 25\text{ °C}$; unclamped; $t_p = 54\text{ μs}$; Fig. 4	[1]	-	93.3	mJ

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Source-drain diode						
Q_r	recovered charge	$I_S = 25 \text{ A}$; $di_S/dt = -100 \text{ A}/\mu\text{s}$; $V_{GS} = 0 \text{ V}$; $V_{DS} = 50 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 18	-	20	-	nC

[1] Protected by 100% test

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 <p>LFAK56; Power-SO8 (SOT669)</p>	 <p>mbb076</p>
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN012-100YSF	LFAK56; Power-SO8	plastic, single-ended surface-mounted package; 4 terminals	SOT669

7. Marking

Table 4. Marking codes

Type number	Marking code
PSMN012-100YSF	12FS10Y

8. Limiting values

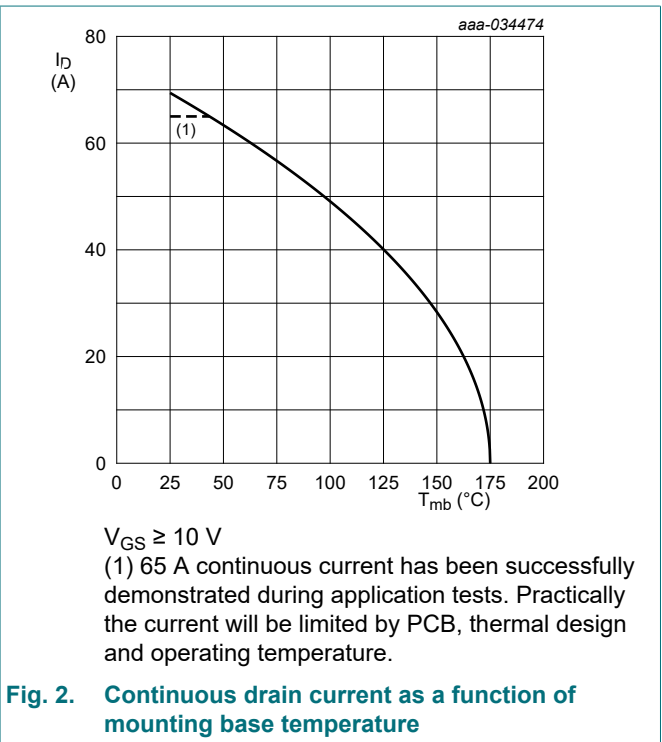
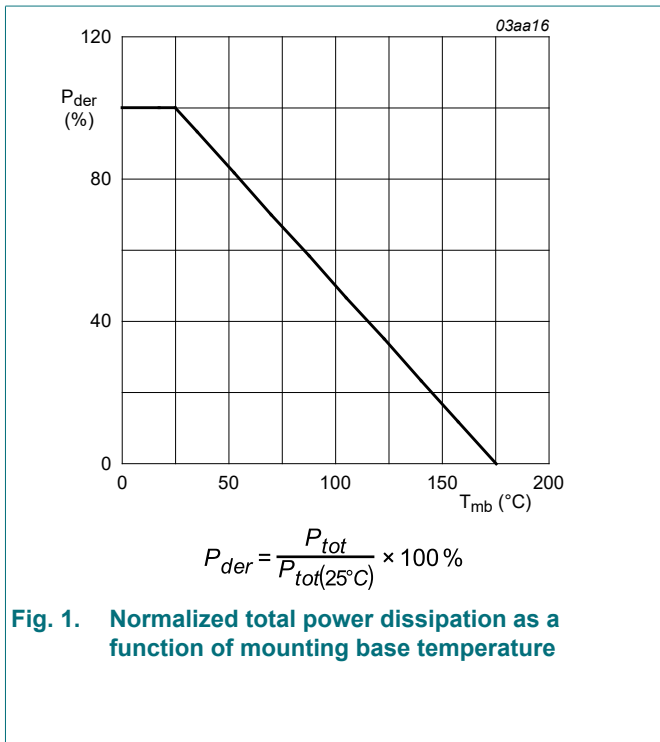
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). $T_j = 25 \text{ }^\circ\text{C}$ unless otherwise stated.

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$25 \text{ }^\circ\text{C} \leq T_j \leq 175 \text{ }^\circ\text{C}$	-	100	V
V_{DGR}	drain-gate voltage	$25 \text{ }^\circ\text{C} \leq T_j \leq 175 \text{ }^\circ\text{C}$; $R_{GS} = 20 \text{ k}\Omega$	-	100	V
V_{GS}	gate-source voltage		-20	20	V
P_{tot}	total power dissipation	$T_{mb} = 25 \text{ }^\circ\text{C}$; Fig. 1	-	130	W
I_D	drain current	$V_{GS} = 10 \text{ V}$; $T_{mb} = 25 \text{ }^\circ\text{C}$; Fig. 2	-	65	A
		$V_{GS} = 10 \text{ V}$; $T_{mb} = 100 \text{ }^\circ\text{C}$; Fig. 2	-	49	A
I_{DM}	peak drain current	pulsed; $t_p \leq 10 \text{ }\mu\text{s}$; $T_{mb} = 25 \text{ }^\circ\text{C}$; Fig. 3	-	278	A
T_{stg}	storage temperature		-55	175	$^\circ\text{C}$
T_j	junction temperature		-55	175	$^\circ\text{C}$

Symbol	Parameter	Conditions		Min	Max	Unit
$T_{\text{slid(M)}}$	peak soldering temperature			-	260	°C
Source-drain diode						
I_S	source current	$T_{\text{mb}} = 25\text{ °C}$		-	65	A
I_{SM}	peak source current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{\text{mb}} = 25\text{ °C}$		-	278	A
Avalanche ruggedness						
$E_{\text{DS(AL)S}}$	non-repetitive drain-source avalanche energy	$I_D = 27.8\text{ A}$; $V_{\text{sup}} \leq 100\text{ V}$; $R_{\text{GS}} = 50\text{ }\Omega$; $V_{\text{GS}} = 10\text{ V}$; $T_{\text{J(init)}} = 25\text{ °C}$; unclamped; $t_p = 54\text{ }\mu\text{s}$; Fig. 4	[1]	-	93.3	mJ
I_{AS}	non-repetitive avalanche current	$V_{\text{sup}} \leq 100\text{ V}$; $V_{\text{GS}} = 10\text{ V}$; $T_{\text{J(init)}} = 25\text{ °C}$; $R_{\text{GS}} = 50\text{ }\Omega$; Fig. 4	[1]	-	26.4	A

[1] Protected by 100% test



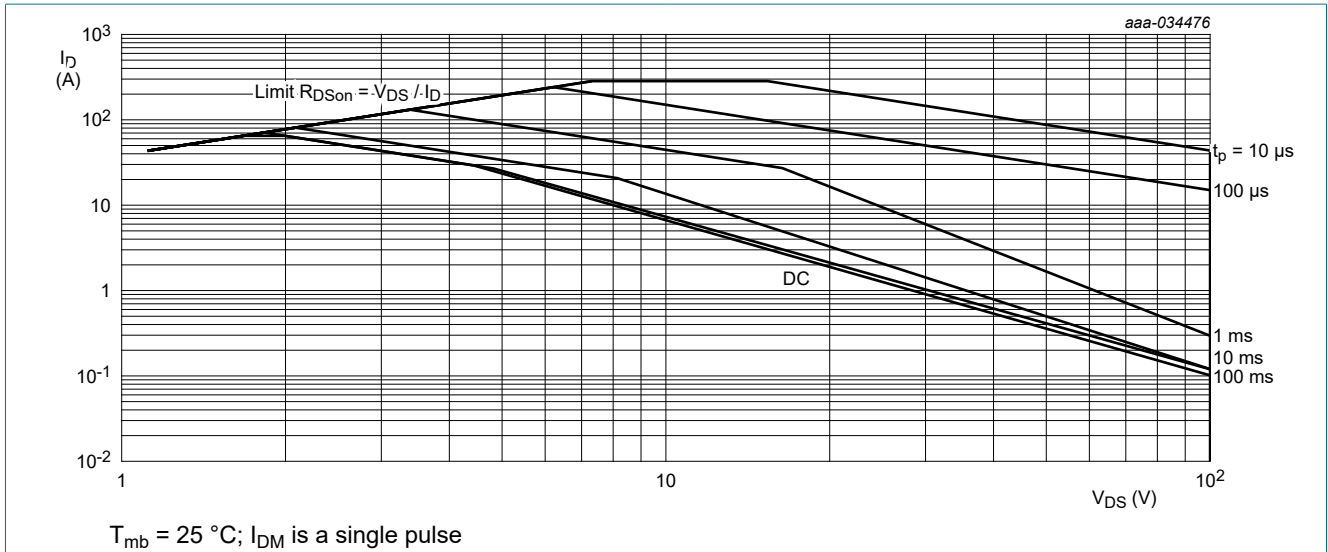


Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

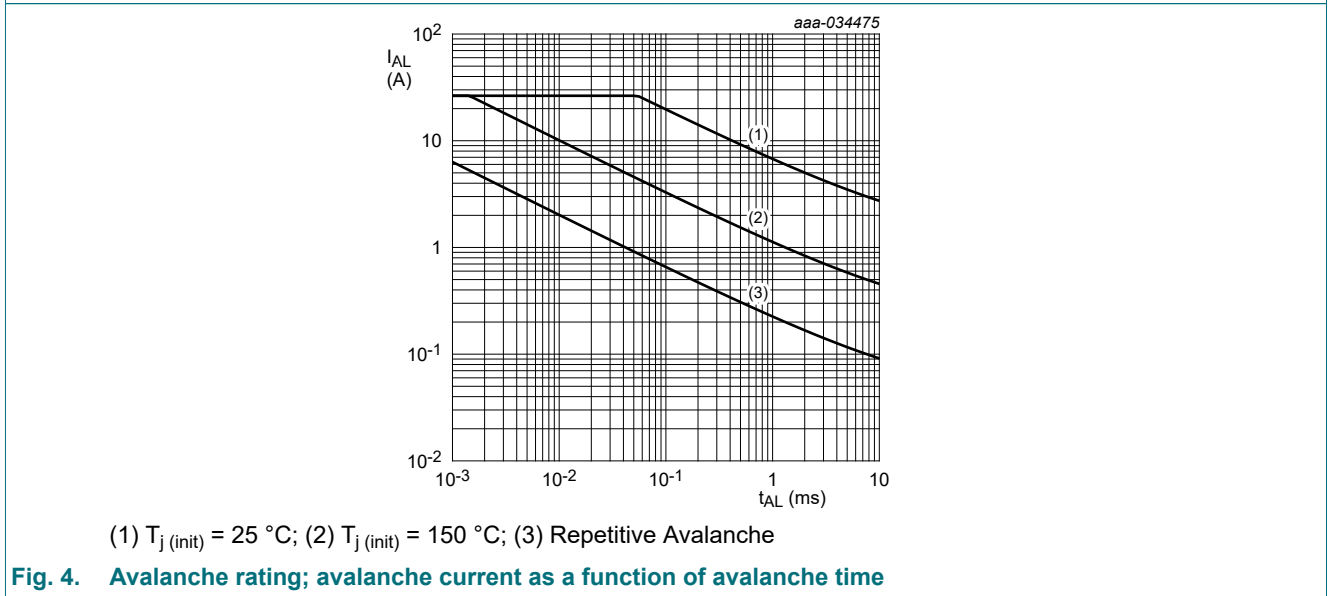


Fig. 4. Avalanche rating; avalanche current as a function of avalanche time

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	1.04	1.16	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	Fig. 6	-	42	-	K/W
		Fig. 7	-	85	-	K/W

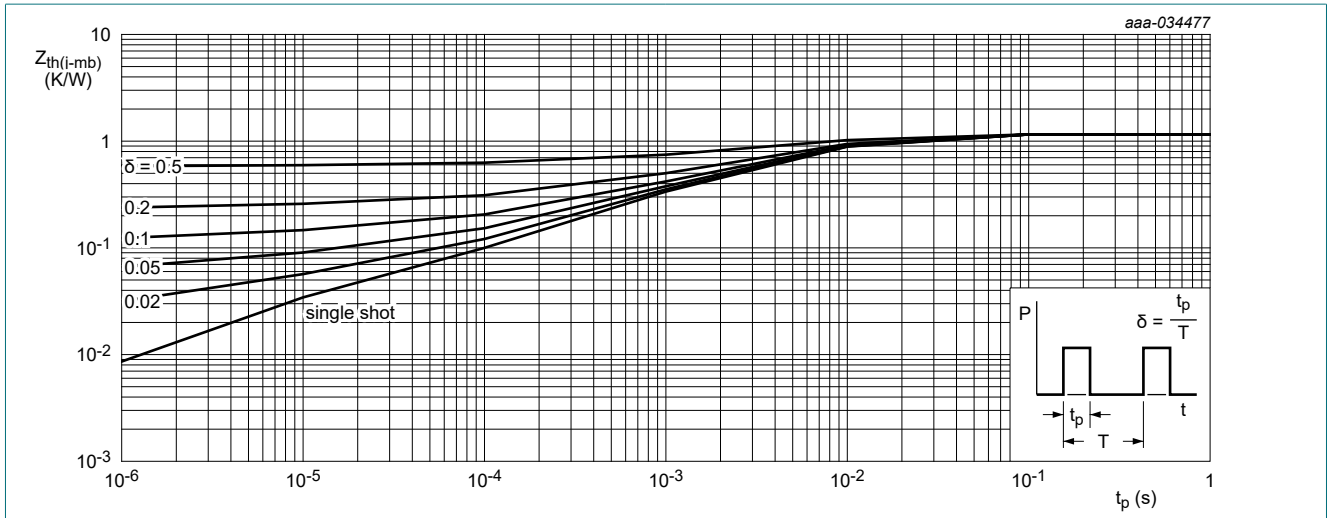


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

aaa-027933

Copper area 25.4 mm square; 70 μm thick on FR4 board

aaa-027935

70 μm thick copper on FR4 board

Fig. 6. PCB layout for thermal resistance from junction to ambient

Fig. 7. PCB layout with minimum footprint for thermal resistance from junction to ambient

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$	100	-	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 \text{ }^\circ C$	90	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS}=V_{GS}; T_j = 25 \text{ }^\circ C; \text{ Fig. 11}$	2	3	4	V
		$I_D = 1 \text{ mA}; V_{DS}=V_{GS}; T_j = 175 \text{ }^\circ C$	-	1.7	-	V
		$I_D = 1 \text{ mA}; V_{DS}=V_{GS}; T_j = -55 \text{ }^\circ C$	-	3.3	-	V
$\Delta V_{GS(th)}/\Delta T$	gate-source threshold voltage variation with temperature	$25 \text{ }^\circ C \leq T_j \leq 150 \text{ }^\circ C$	-	-6.8	-	mV/K
I_{DSS}	drain leakage current	$V_{DS} = 100 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ C$	-	0.01	1	μA
		$V_{DS} = 100 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 125 \text{ }^\circ C$	-	4	100	μA
I_{GSS}	gate leakage current	$V_{GS} = 20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ C$	-	2	100	nA
		$V_{GS} = -20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ C$	-	2	100	nA

NextPower 100 V, 11.8 mOhm N-channel MOSFET in LPAK56 package

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 20\text{ A}; T_j = 25\text{ }^\circ\text{C};$ Fig. 12	-	9.7	11.8	m Ω
		$V_{GS} = 7\text{ V}; I_D = 20\text{ A}; T_j = 25\text{ }^\circ\text{C};$ Fig. 12	-	11.4	17.6	m Ω
		$V_{GS} = 10\text{ V}; I_D = 20\text{ A}; T_j = 100\text{ }^\circ\text{C};$ Fig. 13	-	15	18.8	m Ω
		$V_{GS} = 10\text{ V}; I_D = 20\text{ A}; T_j = 175\text{ }^\circ\text{C};$ Fig. 13	-	21.5	26.8	m Ω
R_G	gate resistance	$f = 1\text{ MHz}; T_j = 25\text{ }^\circ\text{C}$	0.77	1.54	3.1	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 20\text{ A}; V_{DS} = 50\text{ V}; V_{GS} = 10\text{ V};$ $T_j = 25\text{ }^\circ\text{C};$ Fig. 14; Fig. 15	14.6	29	44	nC
		$I_D = 0\text{ A}; V_{DS} = 0\text{ V}; V_{GS} = 10\text{ V};$ $T_j = 25\text{ }^\circ\text{C}$	-	15.5	-	nC
Q_{GS}	gate-source charge	$I_D = 20\text{ A}; V_{DS} = 50\text{ V}; V_{GS} = 10\text{ V};$ $T_j = 25\text{ }^\circ\text{C};$ Fig. 14; Fig. 15	5.3	8.9	12.4	nC
$Q_{GS(th)}$	pre-threshold gate-source charge		-	5.8	-	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge		-	3.1	-	nC
Q_{GD}	gate-drain charge		1.7	5.6	12.8	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 20\text{ A}; V_{DS} = 50\text{ V}; T_j = 25\text{ }^\circ\text{C};$ Fig. 14; Fig. 15	-	4.7	-	V
C_{iss}	input capacitance	$V_{DS} = 50\text{ V}; V_{GS} = 0\text{ V}; f = 1\text{ MHz};$ $T_j = 25\text{ }^\circ\text{C};$ Fig. 16	1221	2035	2849	pF
C_{oss}	output capacitance		314	524	837	pF
C_{rss}	reverse transfer capacitance		2	20	53	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 50\text{ V}; R_L = 2.5\text{ }^\circ\Omega; V_{GS} = 10\text{ V};$ $R_{G(ext)} = 5\text{ }^\circ\Omega; T_j = 25\text{ }^\circ\text{C}$	-	9.5	-	ns
t_r	rise time		-	9	-	ns
$t_{d(off)}$	turn-off delay time		-	20	-	ns
t_f	fall time		-	11	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = 20\text{ A}; V_{GS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C};$ Fig. 17	-	0.87	1	V
t_{rr}	reverse recovery time	$I_S = 25\text{ A}; di_S/dt = -100\text{ A}/\mu\text{s}; V_{GS} = 0\text{ V};$ $V_{DS} = 50\text{ V}; T_j = 25\text{ }^\circ\text{C};$ Fig. 18	-	29	-	ns
Q_r	recovered charge		-	20	-	nC

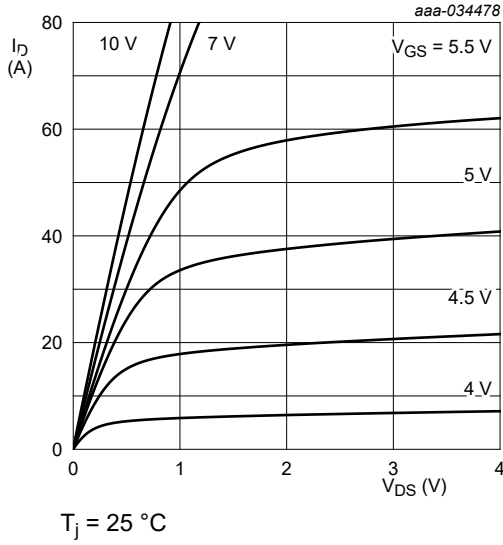


Fig. 8. Output characteristics; drain current as a function of drain-source voltage; typical values

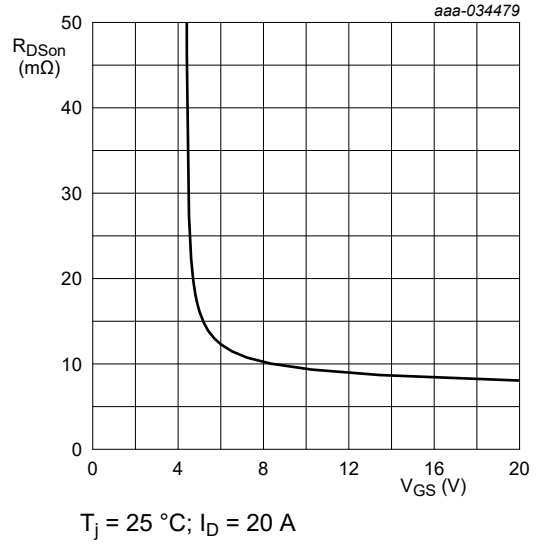


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

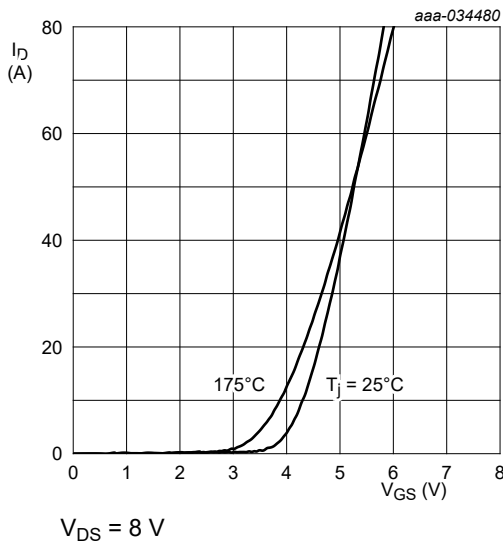


Fig. 10. Transfer characteristics; drain current as a function of gate-source voltage; typical values

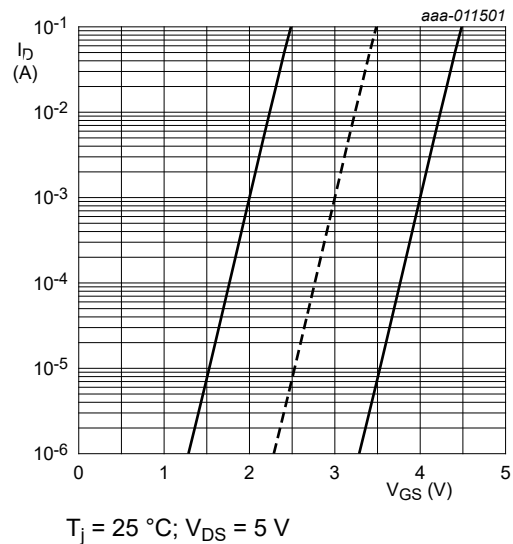


Fig. 11. Sub-threshold drain current as a function of gate-source voltage

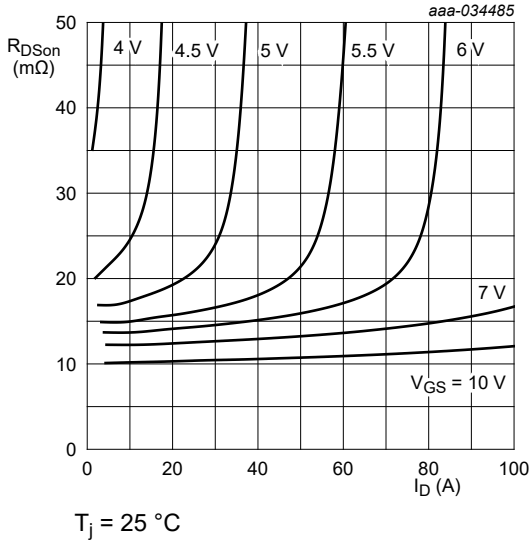
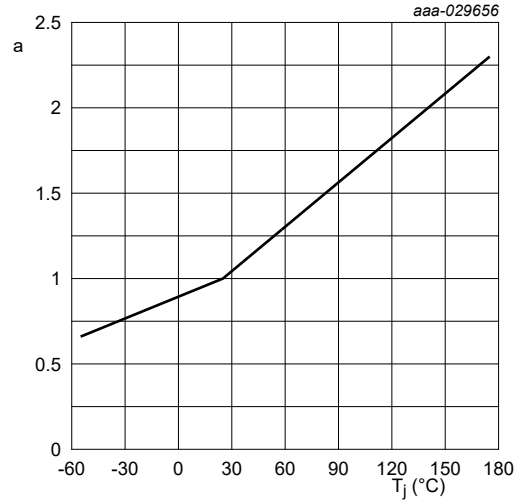


Fig. 12. Drain-source on-state resistance as a function of drain current; typical values



$$a = \frac{R_{DS(on)}}{R_{DS(on)}(25^\circ\text{C})}$$

Fig. 13. Normalized drain-source on-state resistance factor as a function of junction temperature

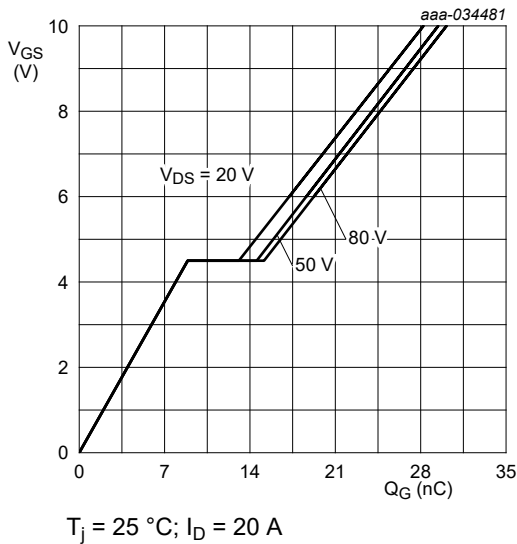


Fig. 14. Gate-source voltage as a function of gate charge; typical values

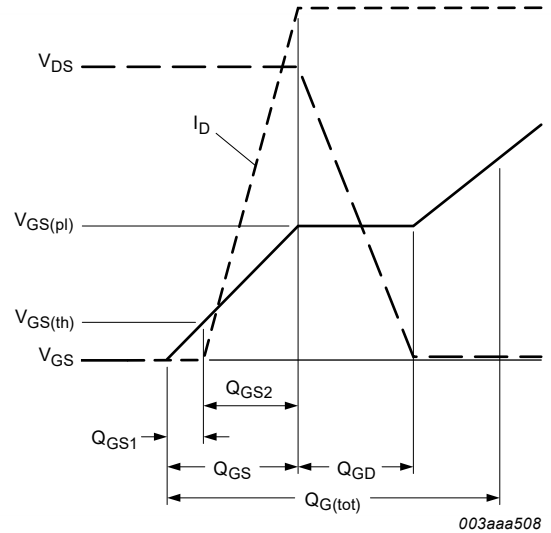
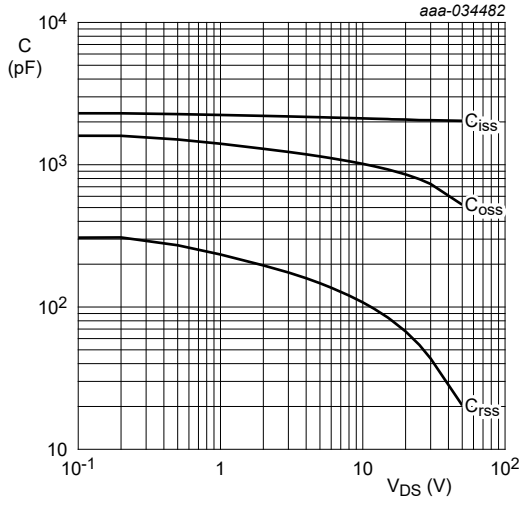
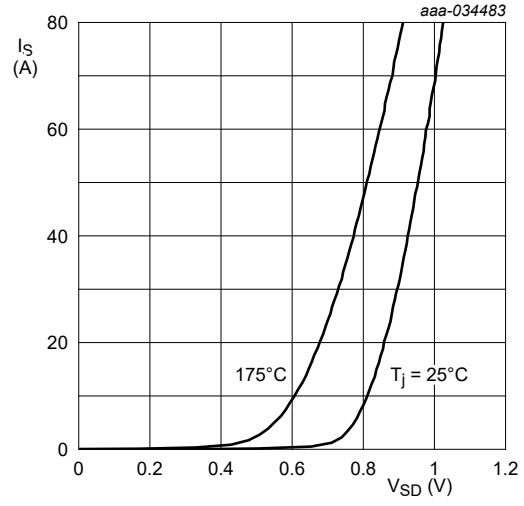


Fig. 15. Gate charge waveform definitions



$V_{GS} = 0$ V; $f = 1$ MHz

Fig. 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$V_{GS} = 0$ V

Fig. 17. Source-drain (diode forward) current as a function of source-drain (diode forward) voltage; typical values

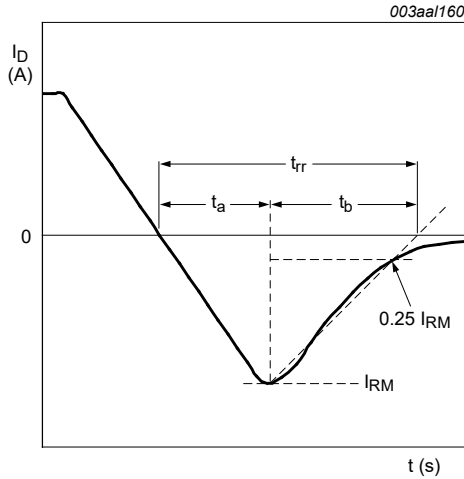


Fig. 18. Reverse recovery timing definition

11. Package outline

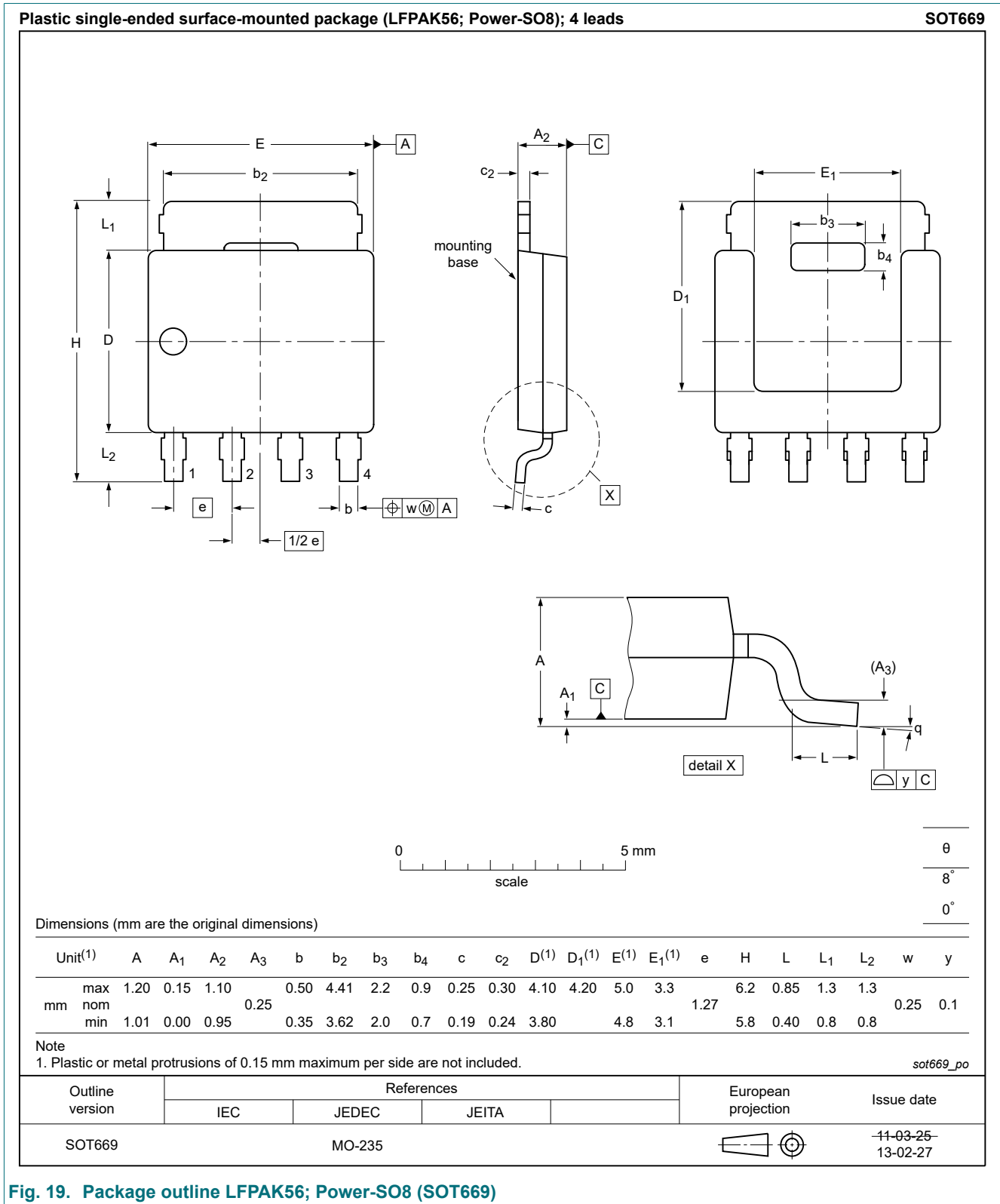


Fig. 19. Package outline LPAK56; Power-SO8 (SOT669)

12. Soldering

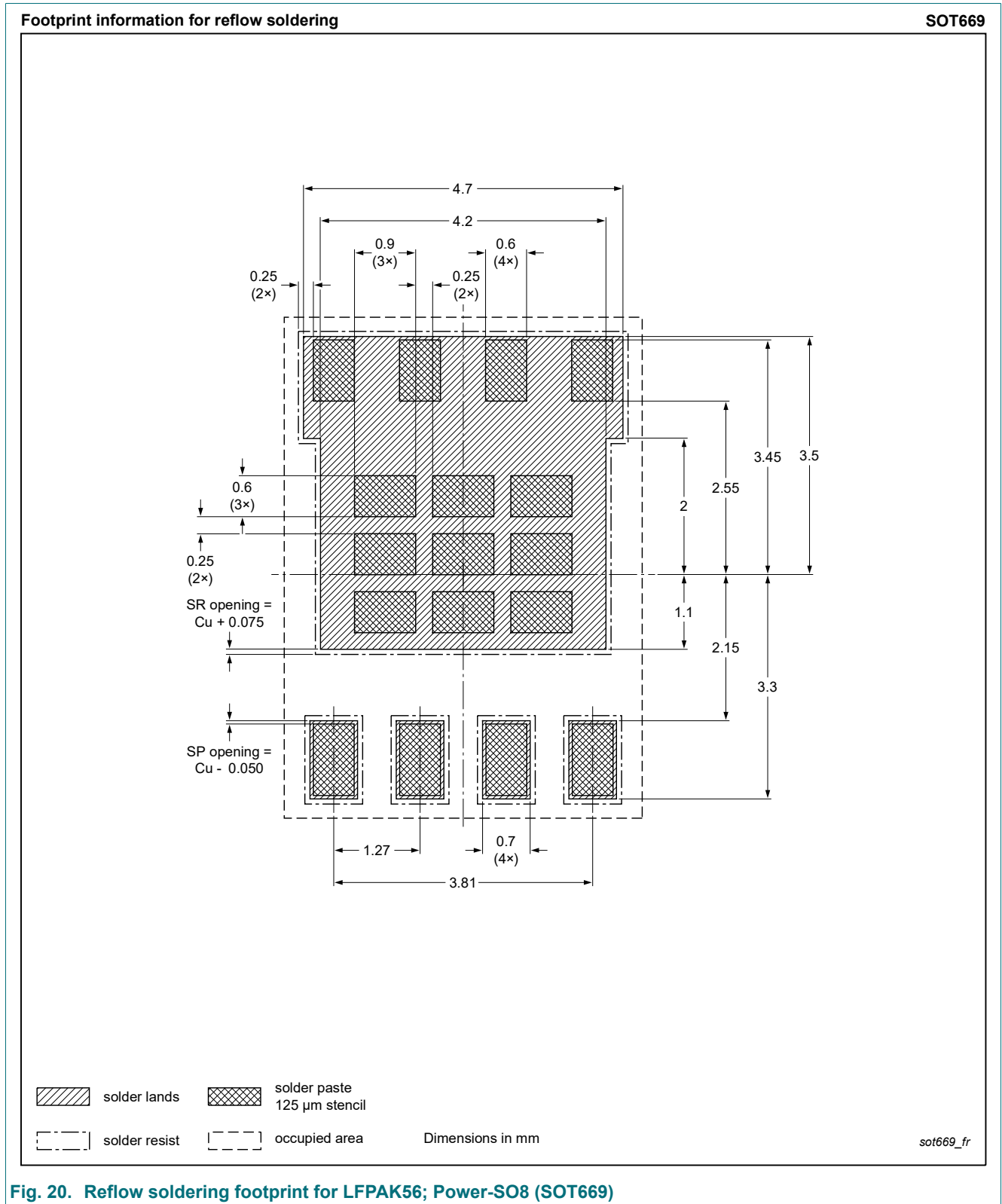
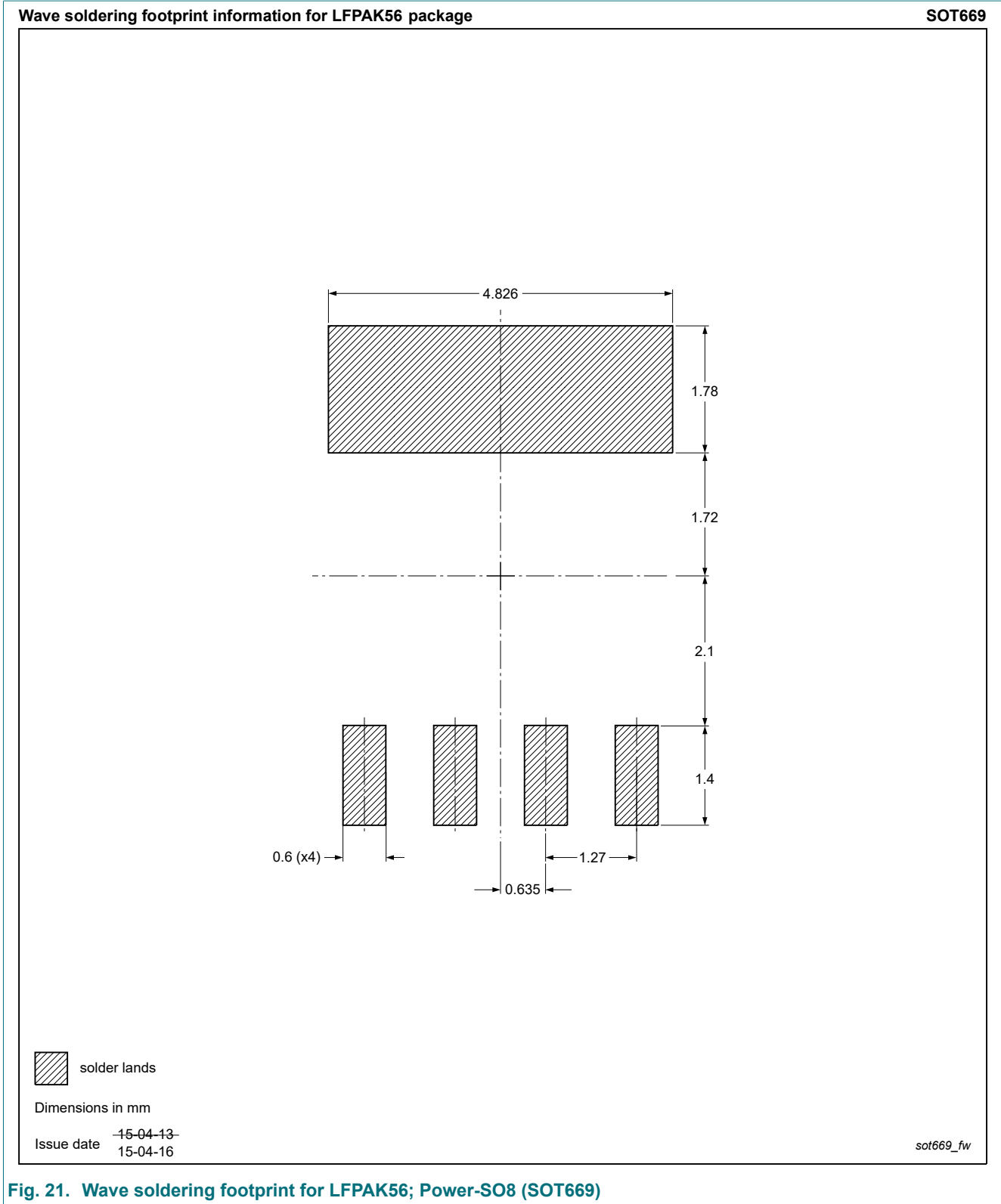


Fig. 20. Reflow soldering footprint for LPAK56; Power-SO8 (SOT669)



13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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